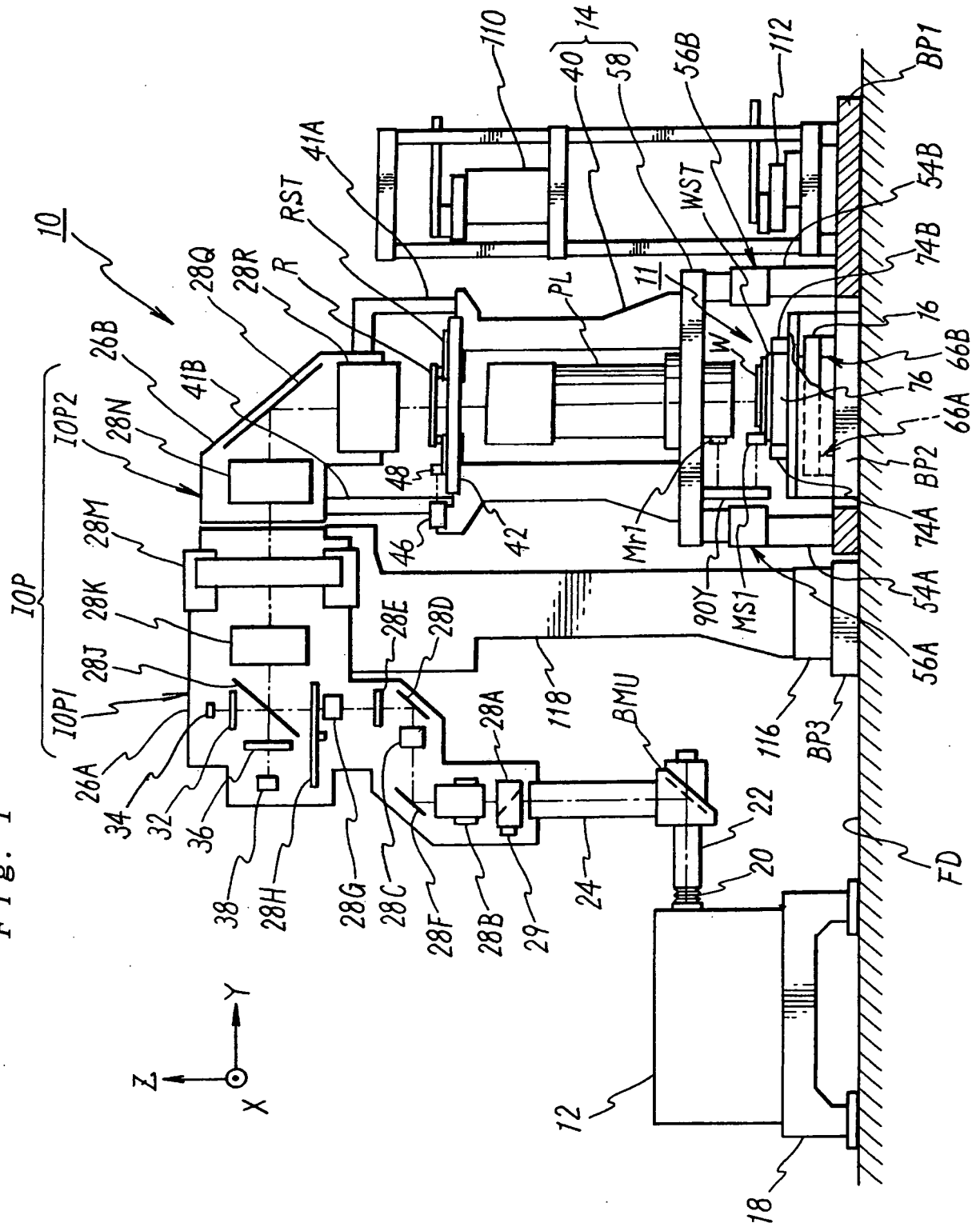


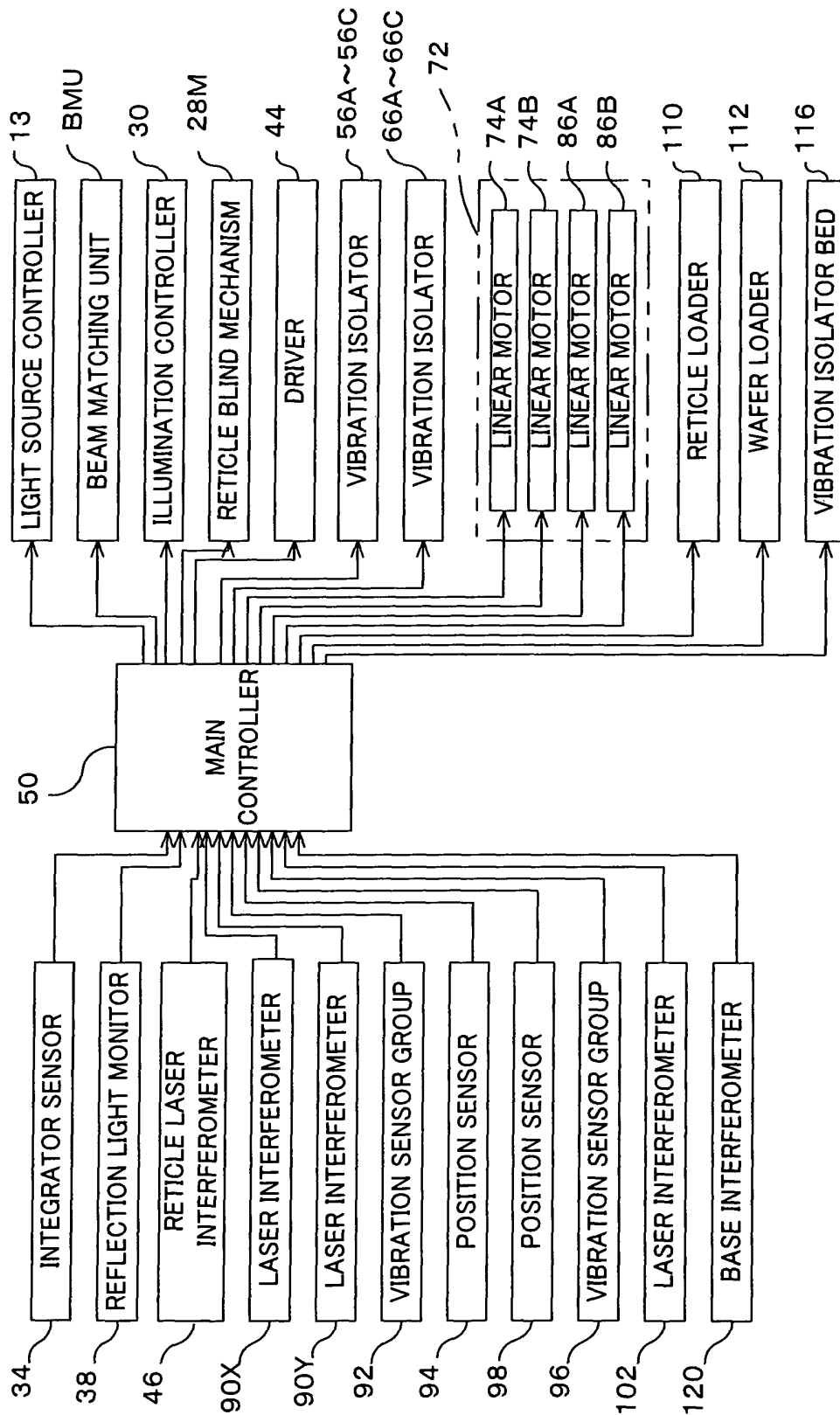
Fig. 1





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Fig. 3



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Fig. 4

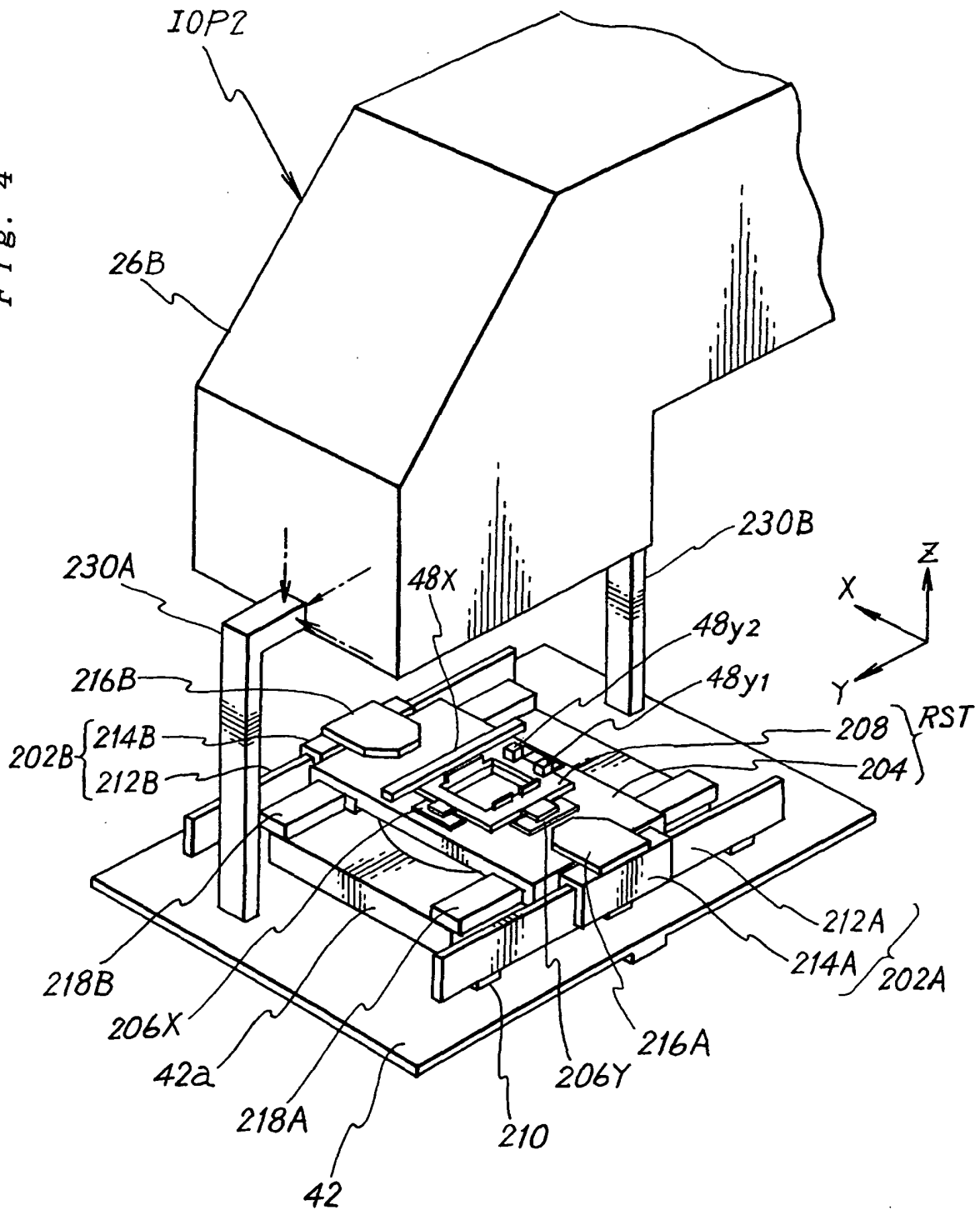
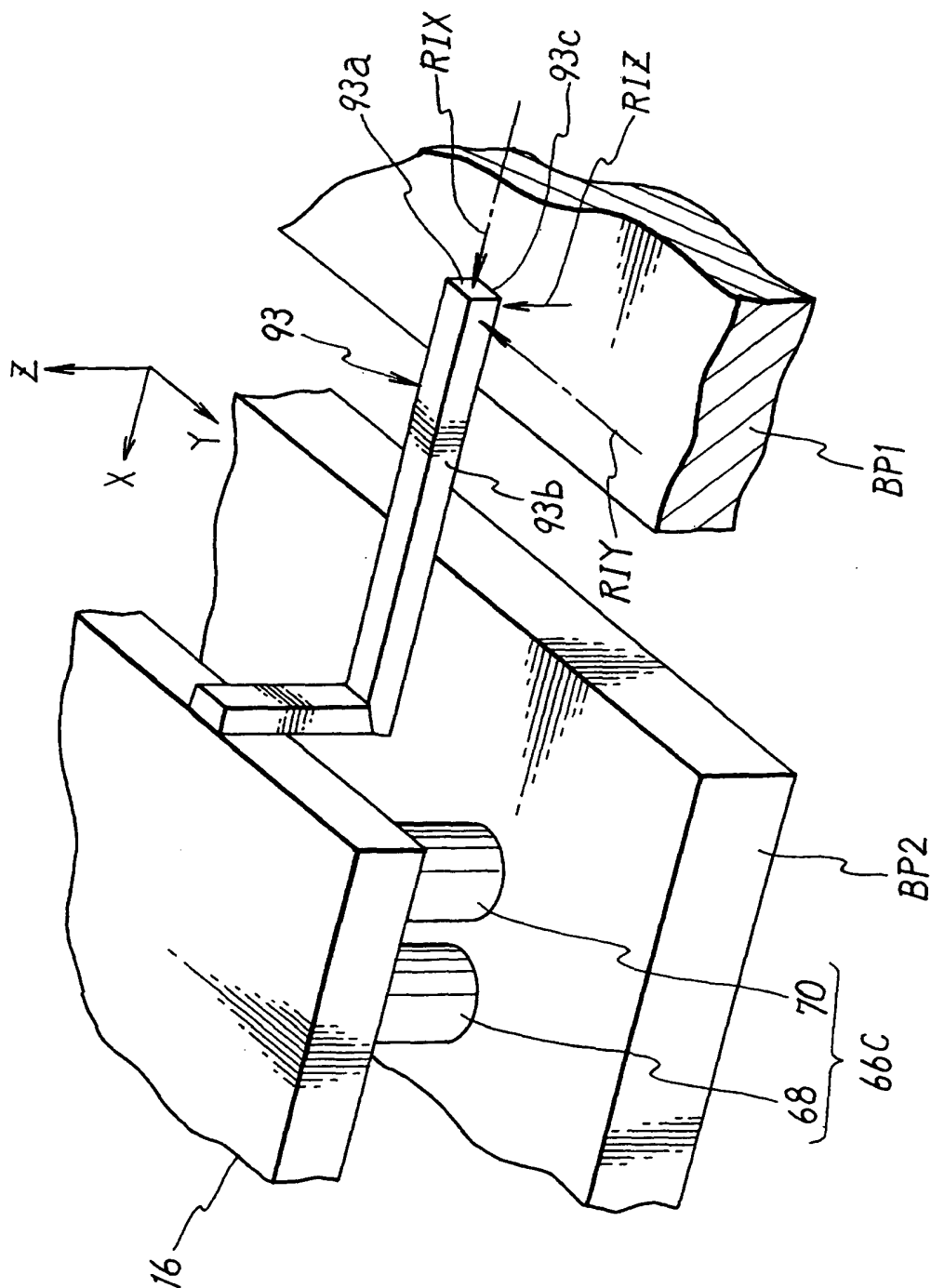
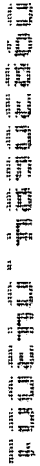


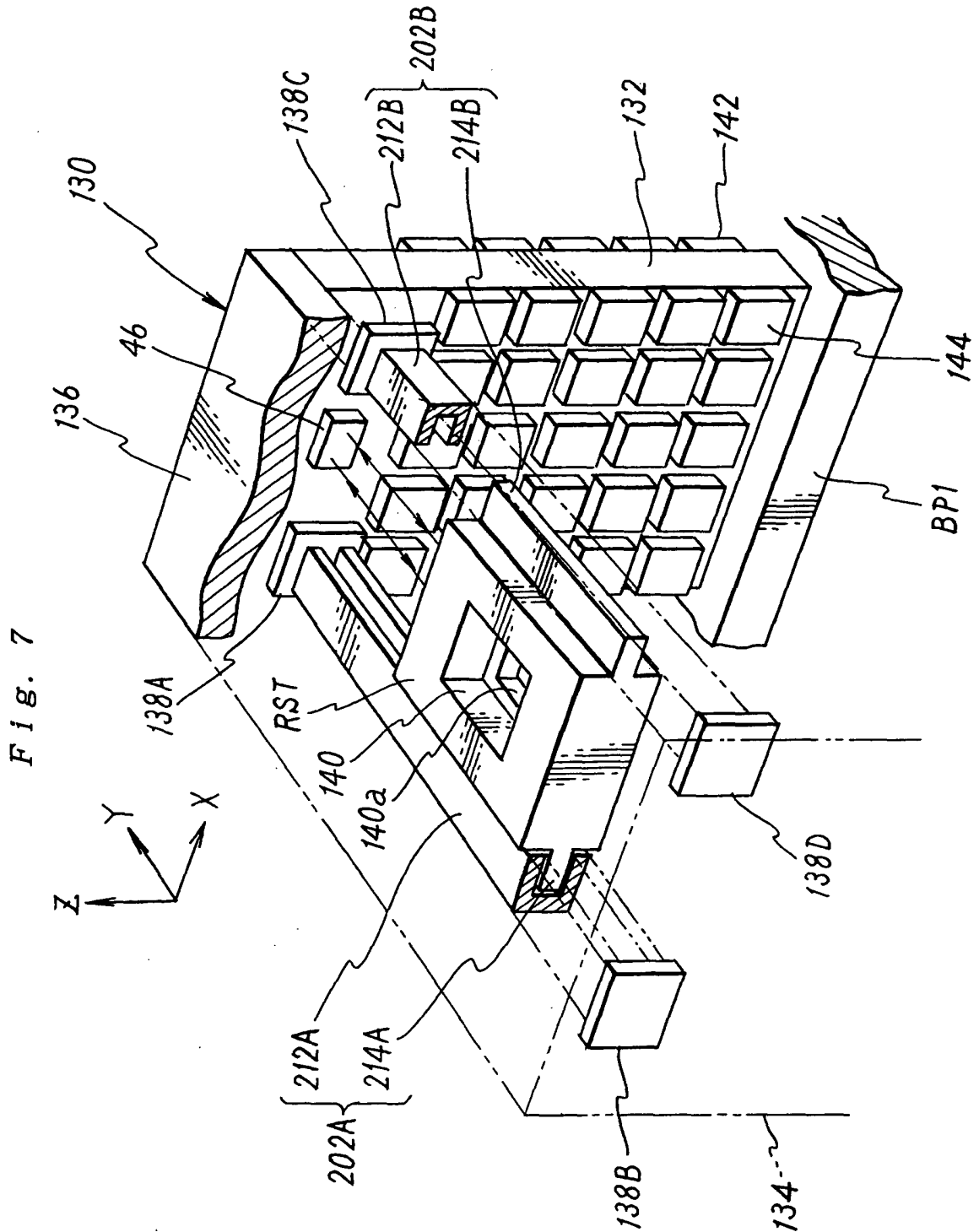
FIG. 4 is a perspective view of the semiconductor device assembly 1000, showing the component 10P2, the base 210, the pillars 230A and 230B, the chip 204, and the various interconnects and pads.



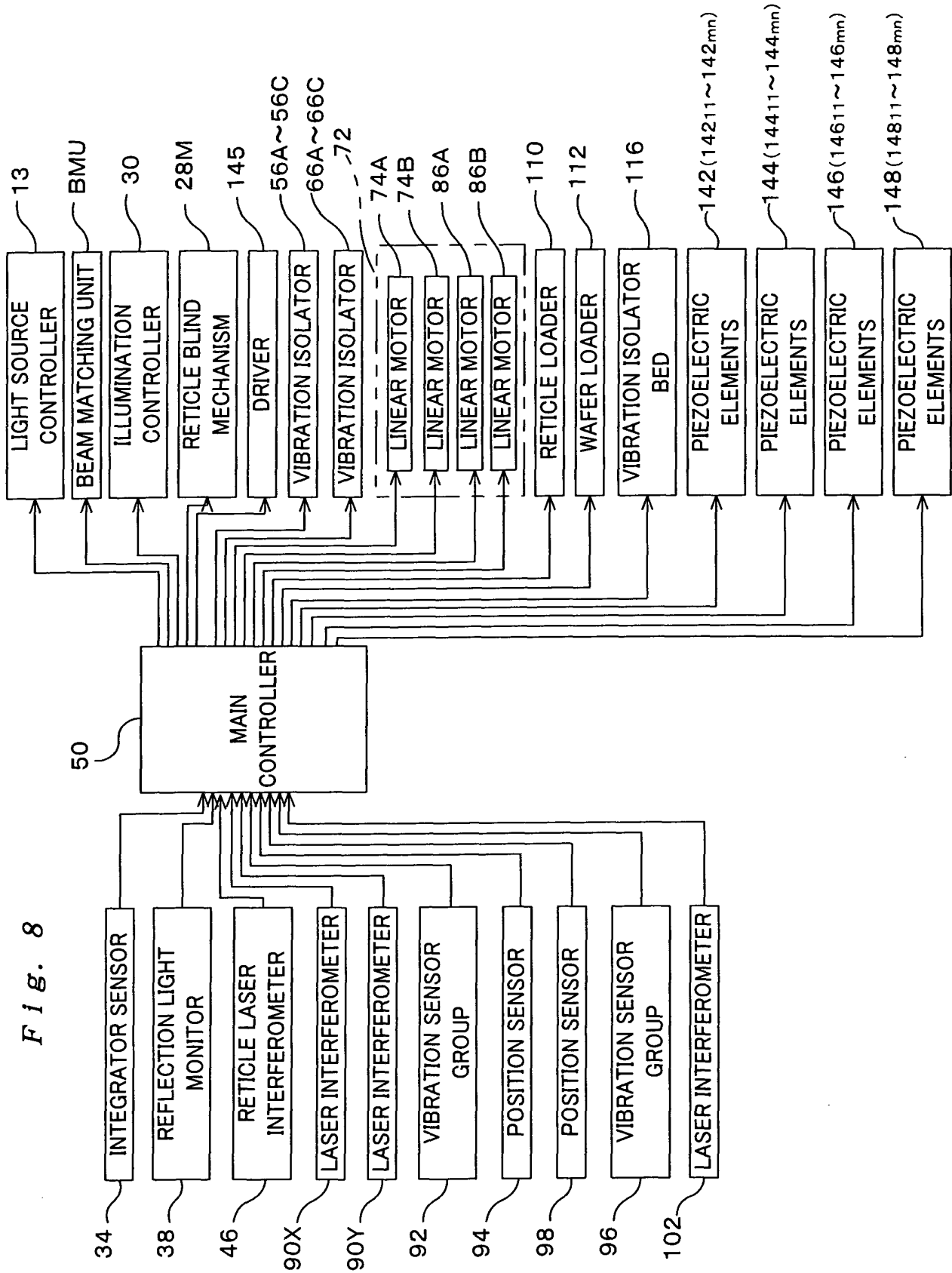
*F i g. 6*



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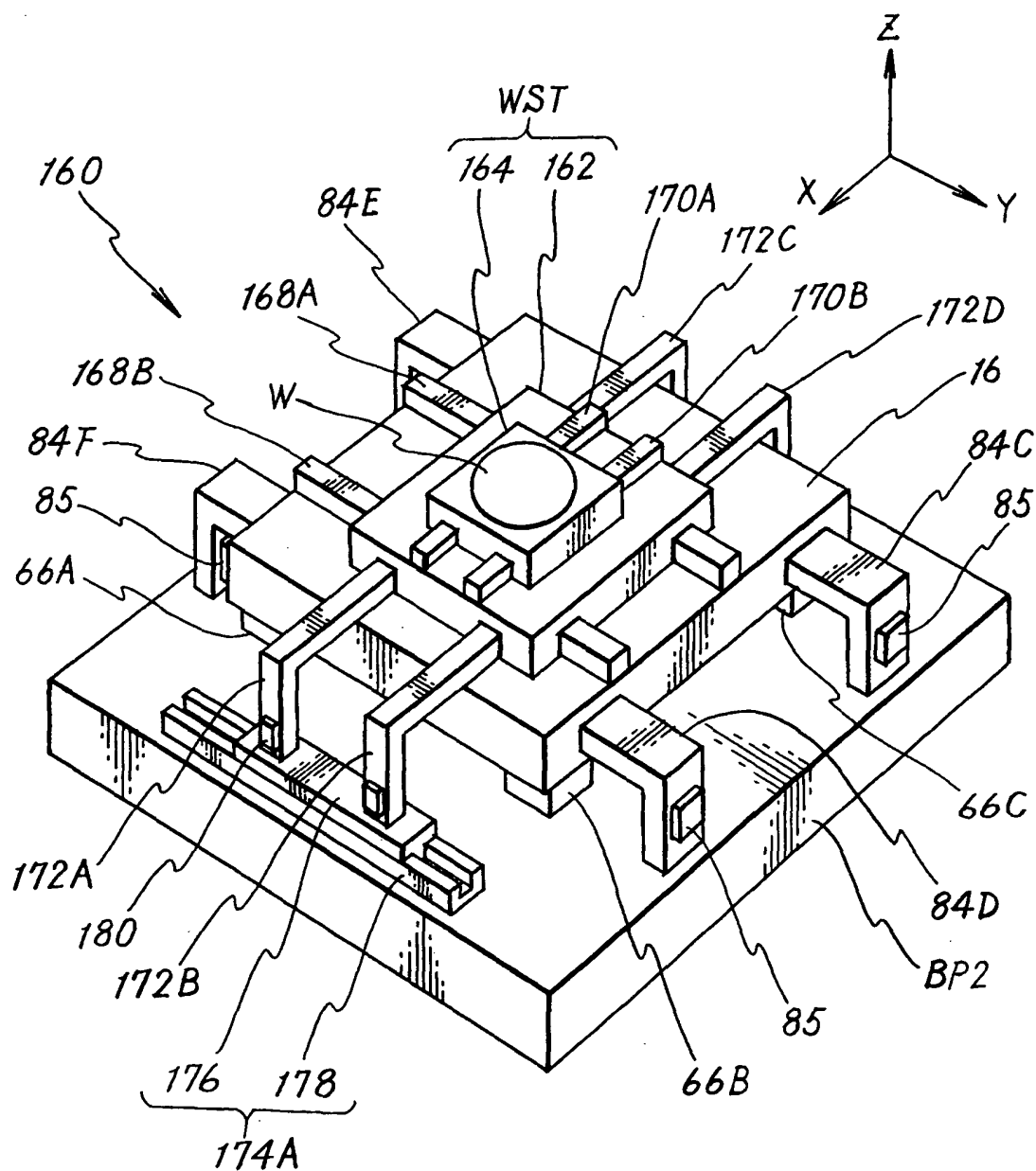


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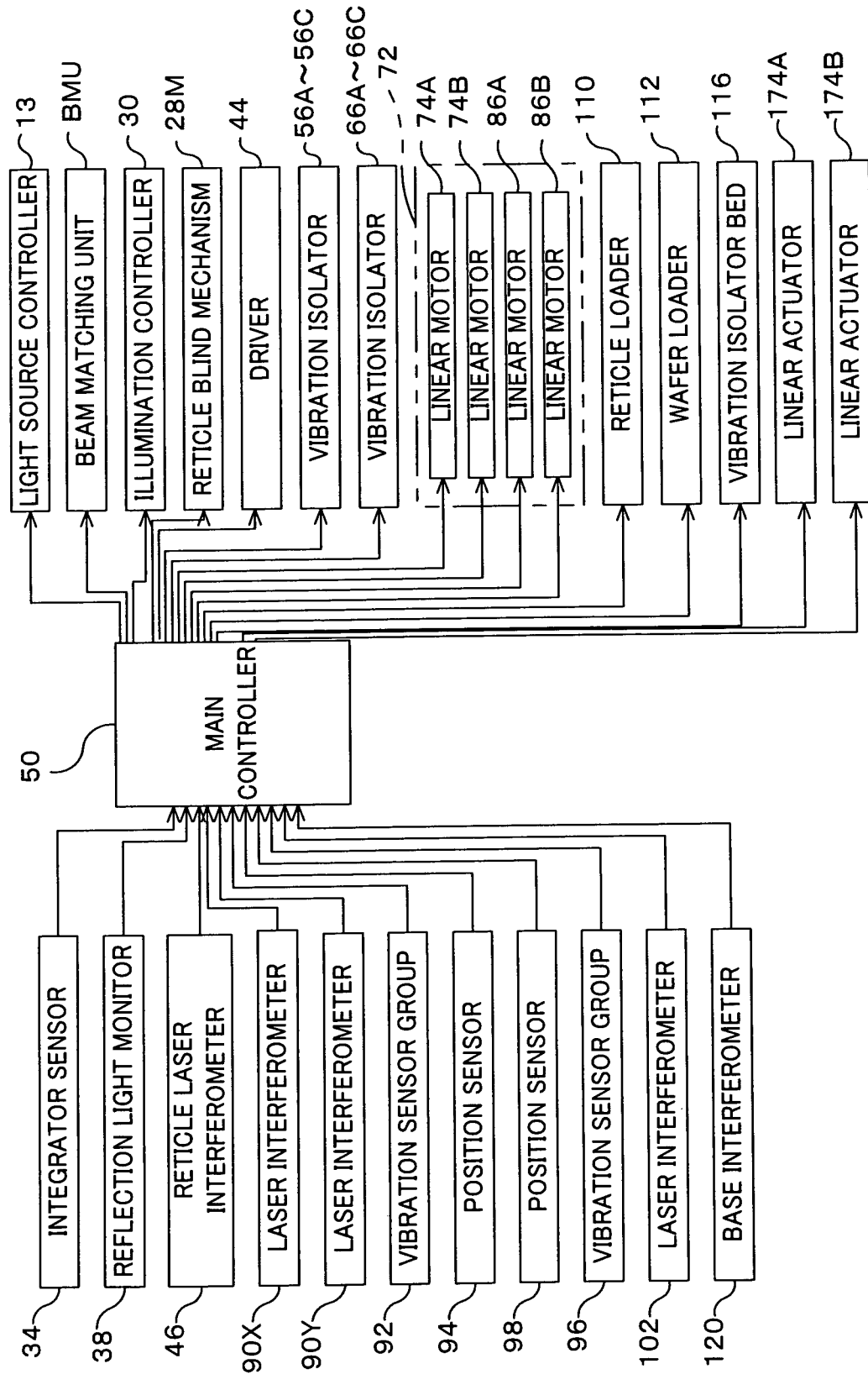


*Fig. 9*



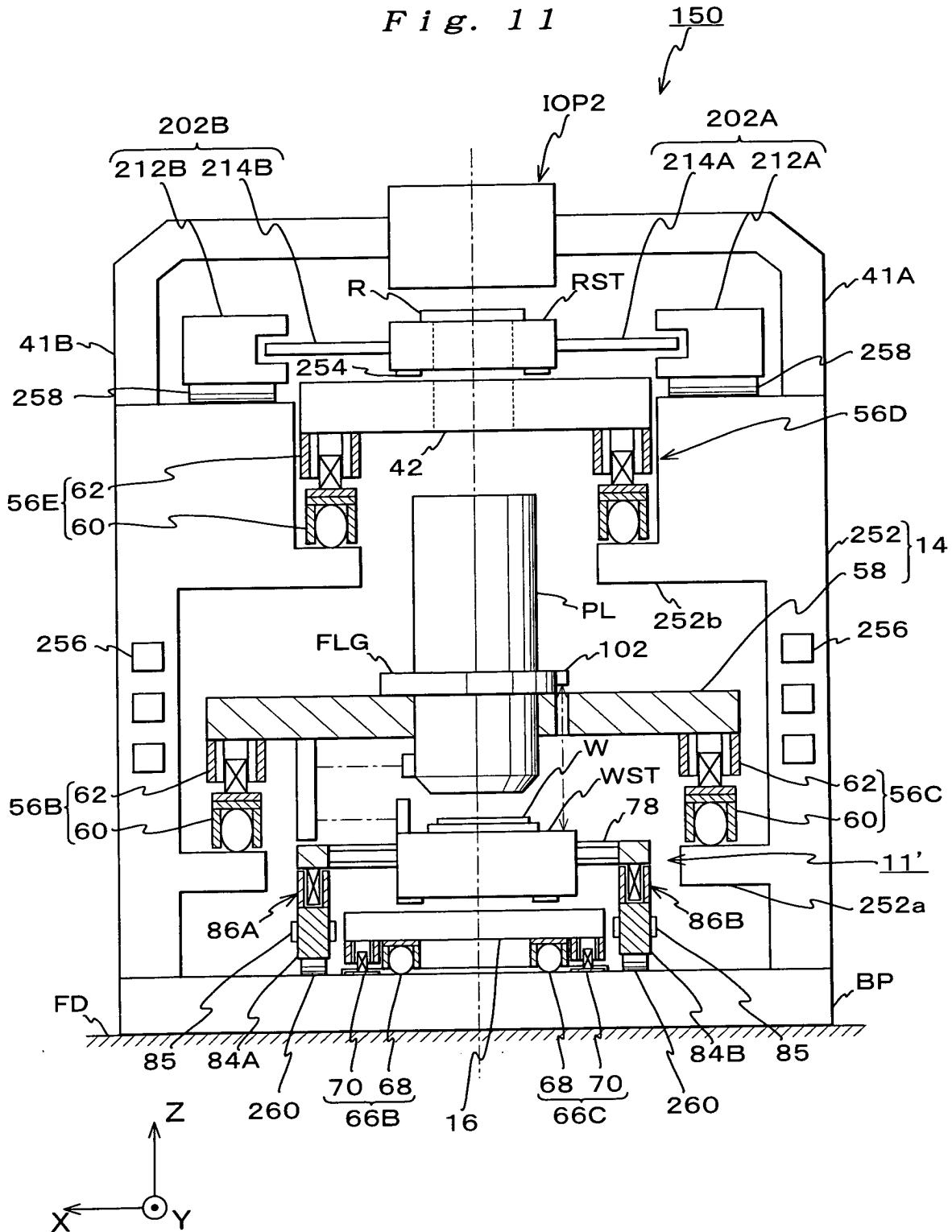
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Fig. 10



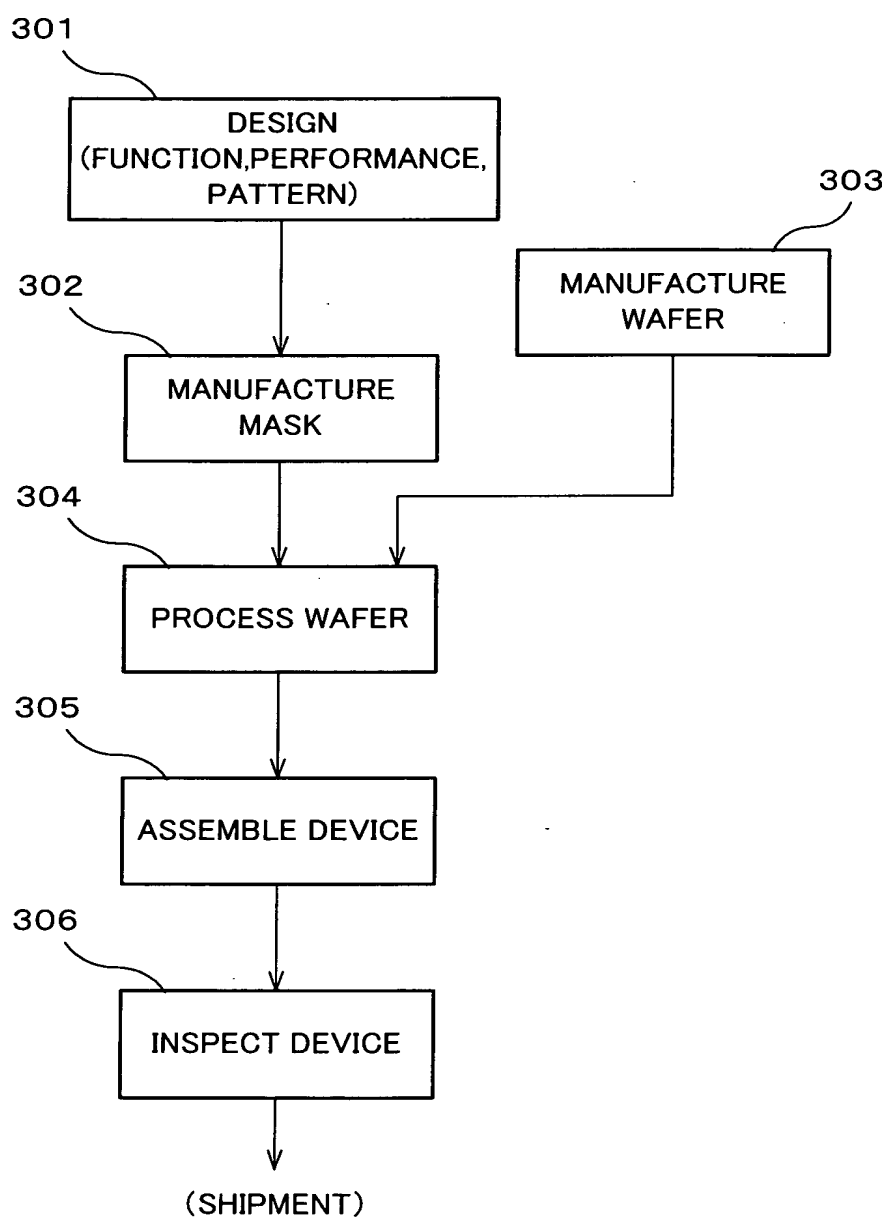
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Fig. 11



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Fig. 12



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Fig. 13

